



Epoxy composites for application in superconducting magnets

Pascal Studer

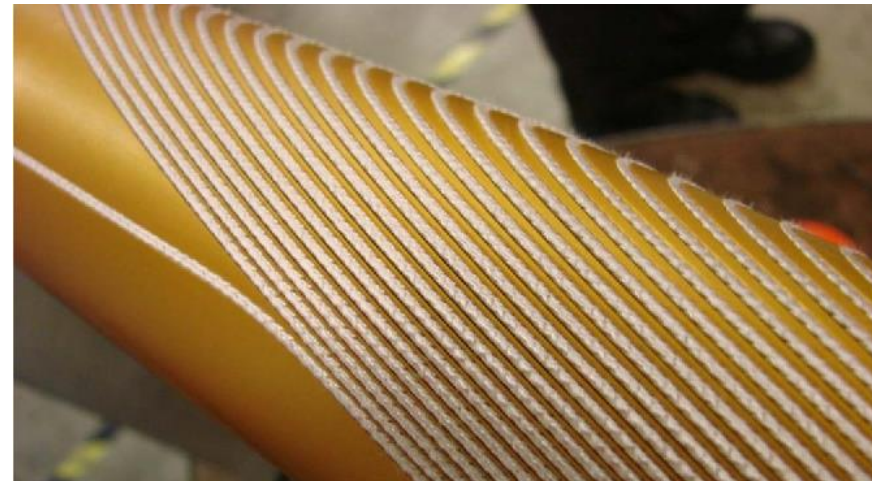
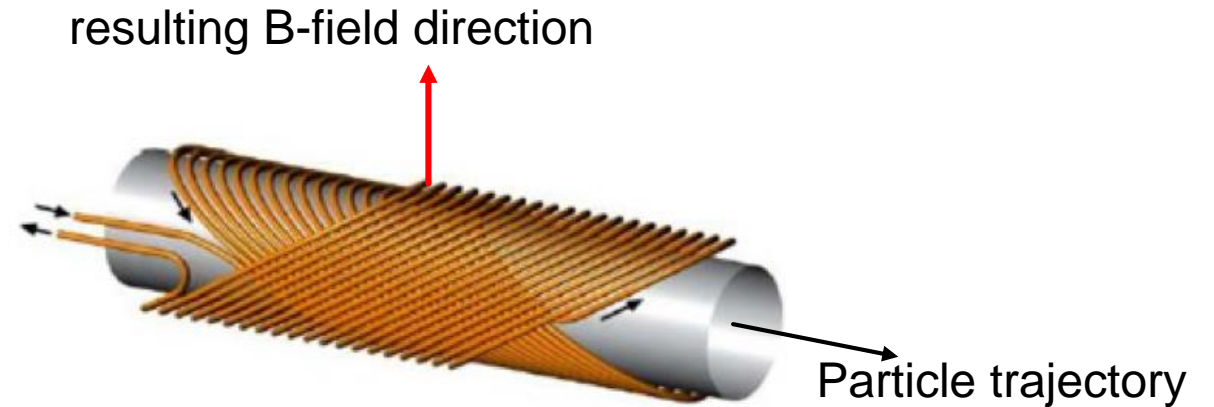
Laboratory for Soft Materials

Structure of the presentation

1. Motivation
2. Engineering approaches
3. Examples / research
4. Experimental tools for preparing SENB samples
5. Conclusion & Outlook

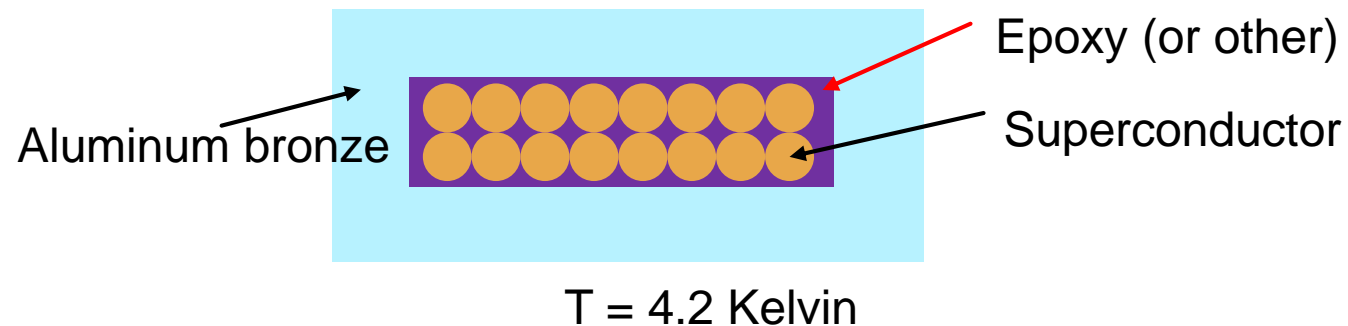
Superconducting electromagnets

- Particles guided by magnetic fields
 - Electromagnets, Lorentz force
 - Operated in the superconducting state at very low temperatures
 - Superconductor: NbTi / Nb₃Sn
- CHART
 - CH-Accelerator Research & Technology
 - Collaboration CERN,ETH, EPFL



Requirements for epoxy application in superconducting magnets

- Function of the epoxy:
 - Keeping the superconductors in place → high modulus, **high fracture toughness**
 - Electrical insulation → Electrical insulator
- Processing requirements
 - No outgassing → Cross-linking without emission of volatiles & low volume change
 - Long pot-life → Low initial viscosity, slow reaction
- Other requirements
 - Radiation stability
 - Operation at cryogenic temp. (~4 K) → matching of thermal expansion coefficients

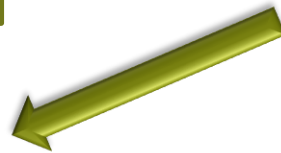


The causal chain of why research is needed

- **Cooling to cryogenic temperature** leads to thermal stresses
- *Strong magnetic fields* exert forces on conductors



- **Above a critical stress**, the material releases elastic energy by **cracking or localized yielding**
- The released energy is dissipated as heat



- Approaching 0 K, heat capacity of almost all materials vanishes
- Thus, cracks and yielding result in **significant local temperature increases at 4 K**



- **Superconductor becomes resistive** above a critical temperature and given current density
- Shutdown of the magnet
- Significant cost factor

Possible approaches to solve the problem

- **Prevent thermal stresses**
- → matching of thermal expansion coefficient to superconductor and metal (outside)

- **Increase K_{Ic}**
- → prevention of cracking
- **Control yielding behaviour**

- **Increase heat capacity**
- → prevent temperature increase to above critical temperature
- **Increase thermal conductivity**
- → reduce the peak temperature

- **Finding new superconductors with higher critical temperature**
- → not part of my work

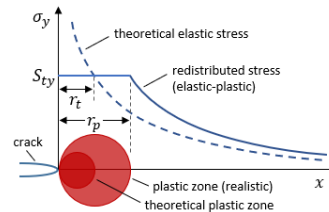
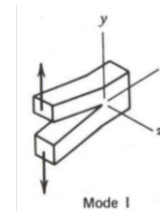
Definition of fracture toughness

- Many engineering materials fail well below their theoretical strength.
- Irwin** found an approximation for the solution near the crack tip:
- Thus, the stresses at a specific location near the crack tip defined by θ and r depend on the factor defined as the stress intensity K_I :
- The singularity at $r=0$ suggests that all materials fail for $a > 0$ and $\sigma_\infty > 0$. However, every material some plasticity or microcracking at the crack tip.
- The critical value of K_I at which failure occurs is an intrinsic material property, the so-called „fracture toughness“ K_{IC} .

$$\sigma_{yy} = \frac{\sigma_\infty \sqrt{\pi a}}{\sqrt{2\pi r}} \cos \frac{\theta}{2} \left(1 + \sin \frac{\theta}{2} \sin \frac{3\theta}{2} \right)$$

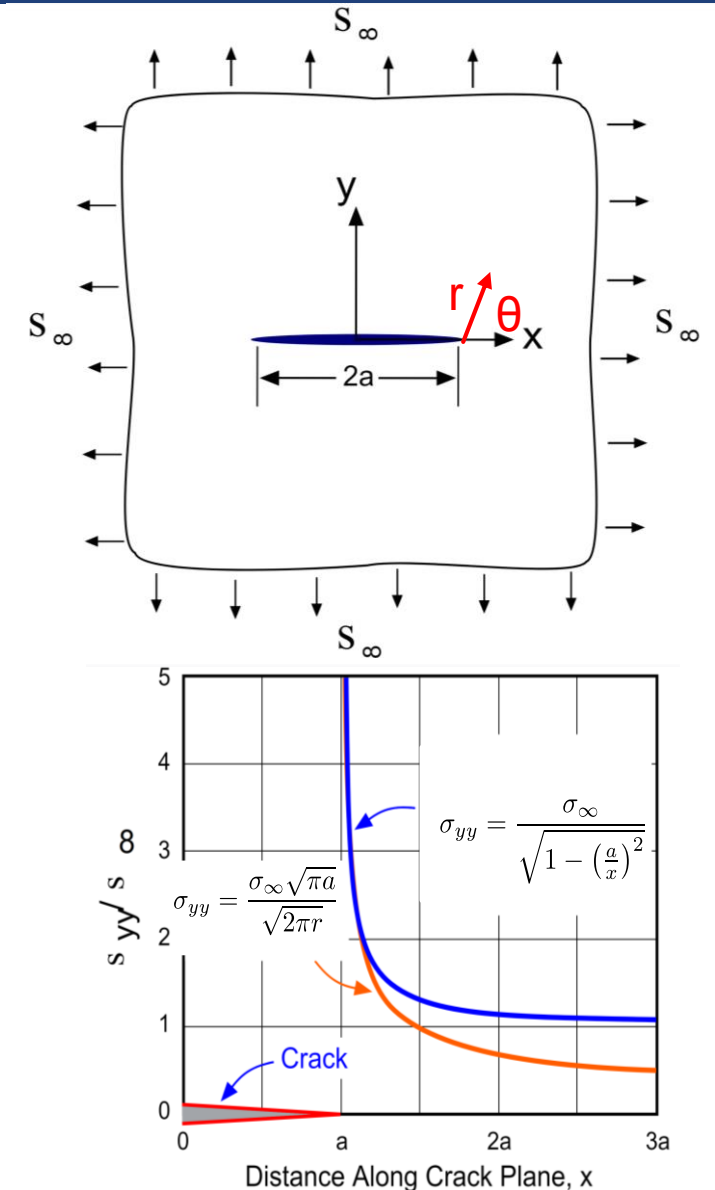
$$K_I := \sigma_\infty \sqrt{\pi a}$$

$$K_I = \sigma_\infty \sqrt{\pi a} \cdot Y$$



$$c = \frac{\pi^2 \sigma_\infty^2 a}{8 \sigma_Y^2} = \frac{\pi}{8} \left(\frac{K_I(\sigma_\infty, a)}{\sigma_Y} \right)^2$$

Plastic zone size, dugdale model
CTD-101K (LN2): 3.07 microns

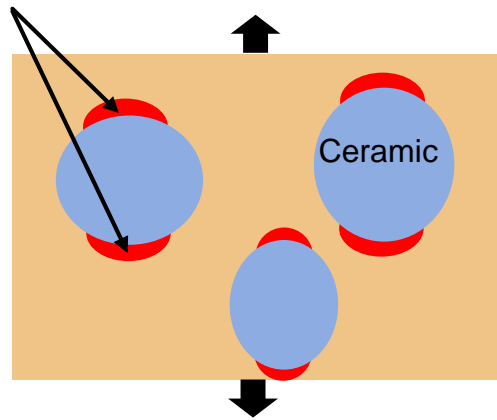


Different ideas of epoxy composites for increasing K1c

Particle toughening

- Incorporate hard particles (micro/nano)
 - **Yielding** of epoxy around particles
 - Crack deflection → increase in crack surface area
- Possible sedimentation (microfillers)
- Possible aggregation (nanofillers/particles)

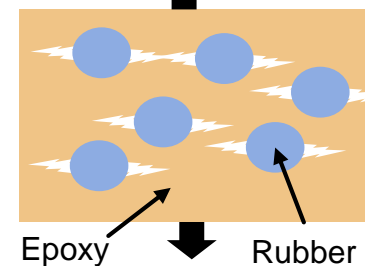
Plane stress – tensile → yielding



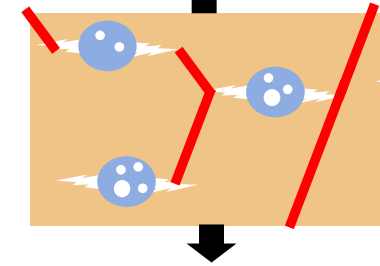
Rubber toughening

- Incorporate soft but tough particles in epoxy matrix
- Different mechanisms
 - **Matrix crazing** (Formation of many small crazes increases energy-release rate, adhesion dependent, low modulus required to prevent debonding particle/matrix)
 - **Shear yielding**: Interaction between stress fields around particles leads to shear bands, acting as an energy-dissipative mechanism, facilitated by cavitation of the rubber (increasing von Mises stress)
- **Not applicable! Below T_g, rubber is not soft anymore**

Matrix crazing



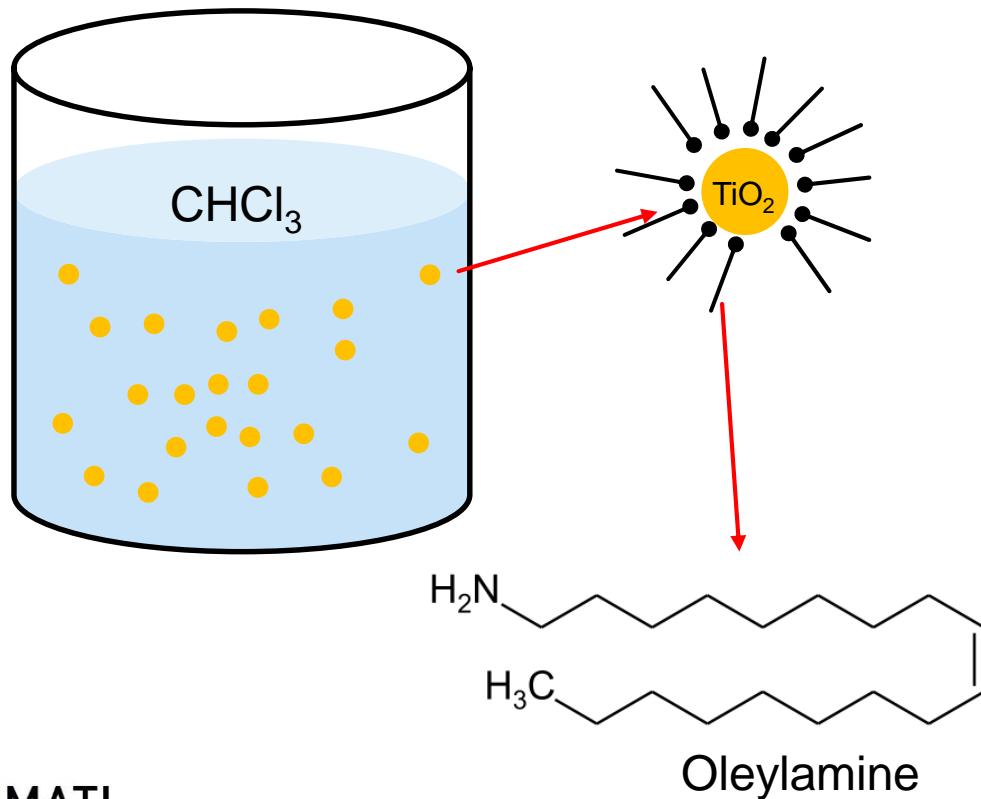
Shear yielding



Epoxy with TiO₂ nanoparticles

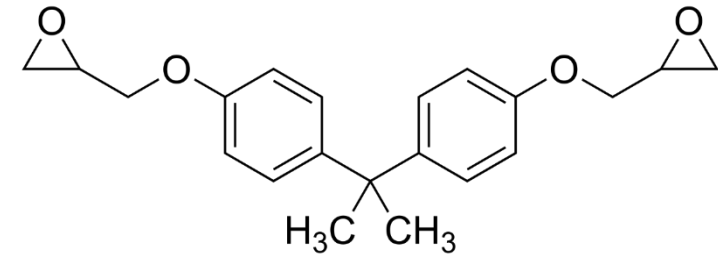
Preparation procedure

1. Nanoparticle suspension

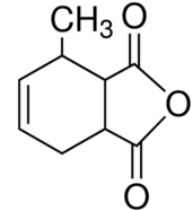
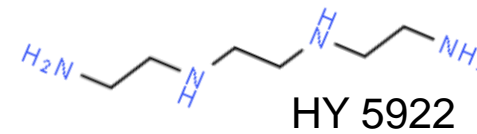


2. Mix particle suspension with hardener or resin

Epoxy resin:



Some hardeners:



CTD-101K Part B

3. Remove CHCl₃ with roto-evap

4. Mix hardener & resin → curing

Epoxy with TiO₂ nanoparticles (MY750 resin)

STEM images: Tecnai F30, FEG, 300 kV (ScopeM)

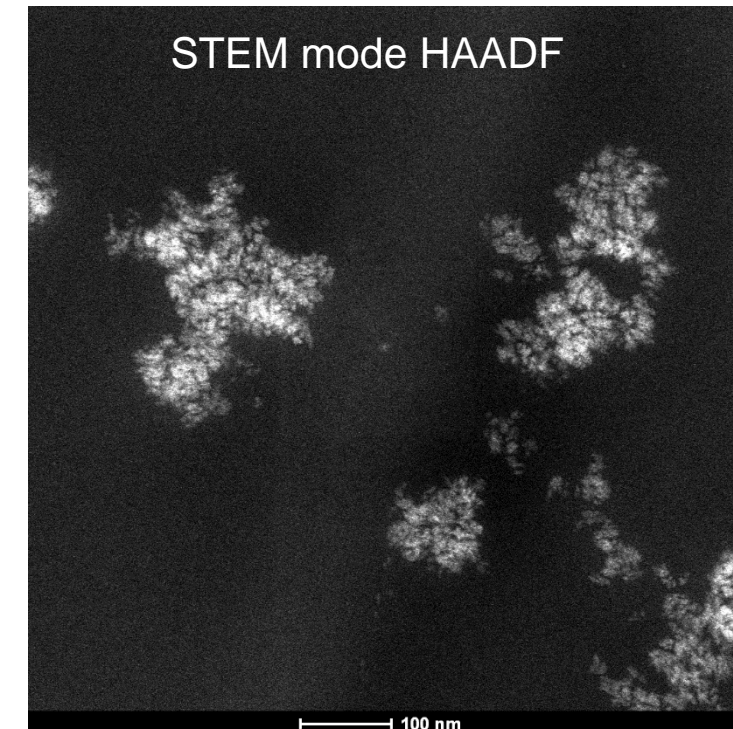
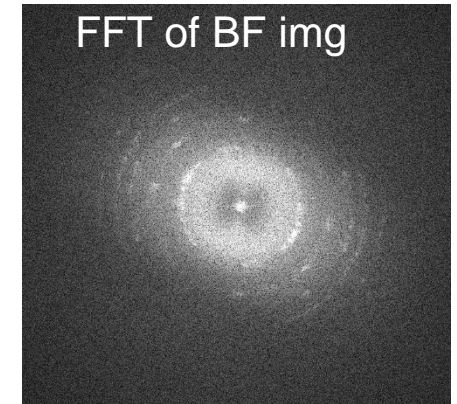
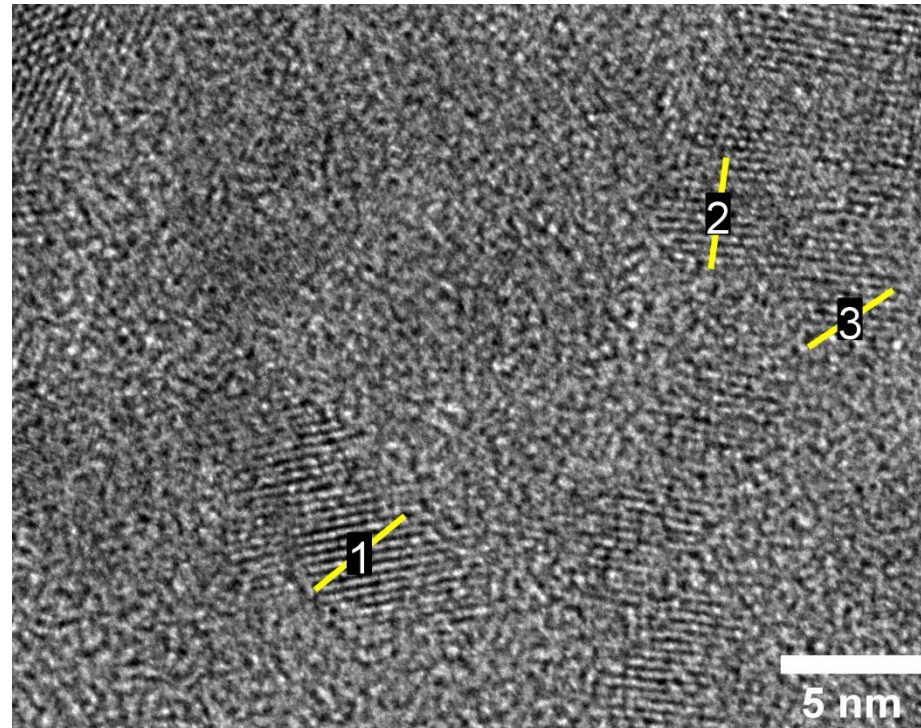
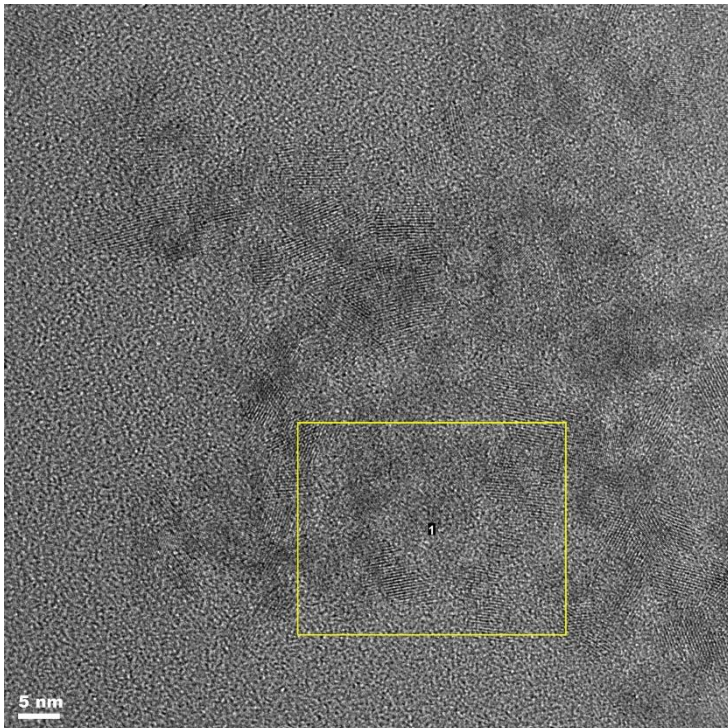
TEM samples prepared by ultramicrotomy

→ Agglomeration

Bright Field

Bright Field, zoom in

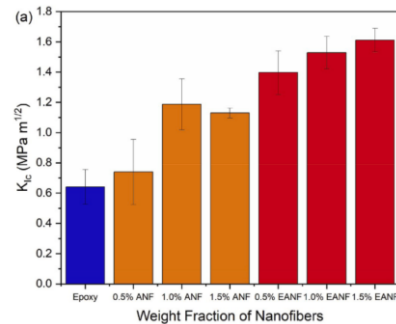
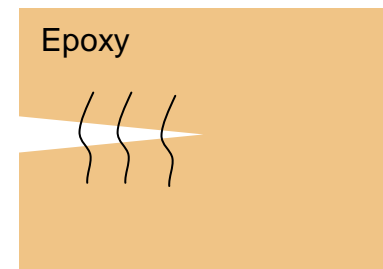
3.9, 3.7, 3.4 nm



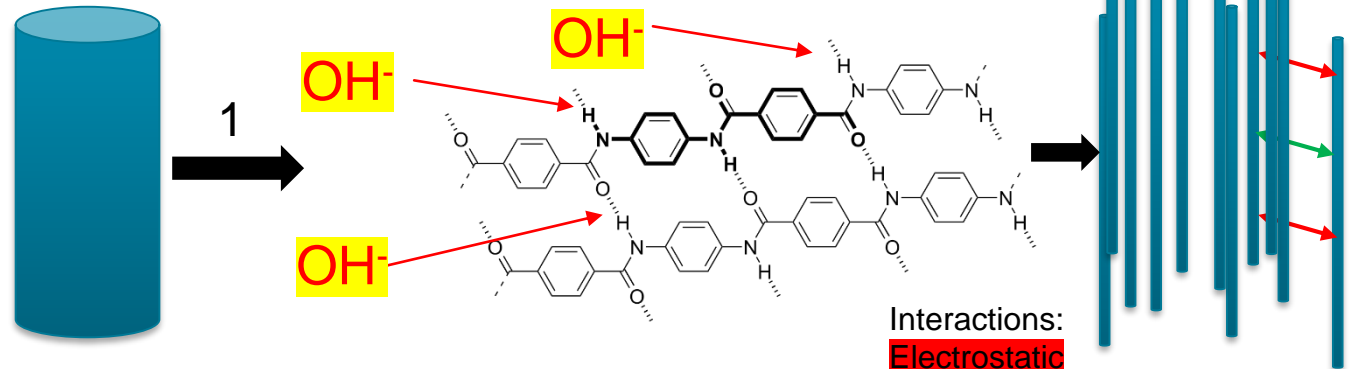
Different ideas of epoxy composites for increasing K1c

Crack bridging

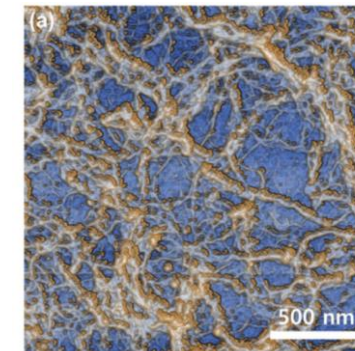
- Epoxy-aramide nanofiber composite
- Toughening by fiber bridging over crack
- Process:
 1. Dissolution of aramide in DMSO/KOH/(H₂O) → polyanion solution
 2. Precipitation by adding proton donor (H₂O)
 3. Filtration / Drying / Characterization
 4. Incorporation into epoxy



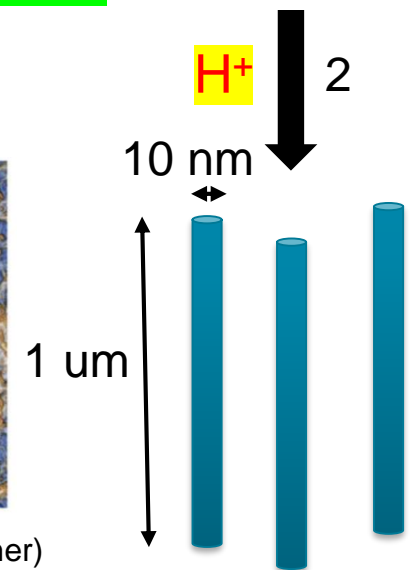
Jung et al., 2020 (Polymer)



Aramide fiber / DMSO /
KOH solution
After stirring for 5 days



Jung et al., 2020 (Polymer)



Results on preparing aramide nanofiber colloidal solutions

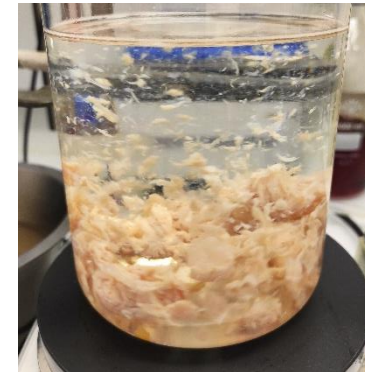
0.2% solution

- 0.2% aramide in DMSO/KOH
- KOH pellets
- Stirred 7 days
- Precipitated with proton donor H₂O (added 0.5 mL/mg of aramide)
- Formation of a colloidal gel











2% solution

- 2.3% aramide in DMSO/H₂O (1:25)
- KOH pellets crushed
- Stirred 9 hours
- Precipitated with proton donor H₂O (added 0.5 mL/mg of aramide)
- Forms clumps
- Problem: Not fully dissolved (next slide) & concentration



Preparation times for aramide polyanion solutions

Composition (1:25 H ₂ O/DMSO), KOH	Preparation method (RT)	6h	24h	
1 % aramide sol.	Stirred, 400 rpm			
1 % aramide sol.	Tumbler, ~80 rpm			
2 % aramide sol.	Tumbler, ~50 rpm			

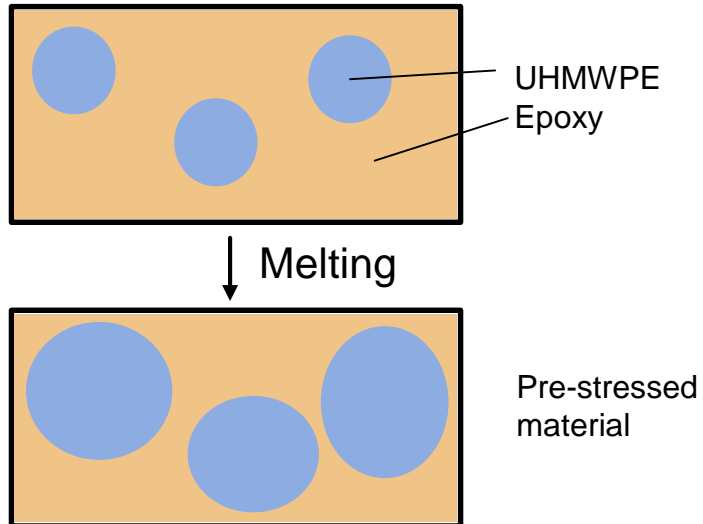
Aramide nanofibers, open questions

- Preparation of dried nanofibers for application from higher concentrated solutions (1%, 2%, 4%,...)
 - What happens when the concentration of proton donor is slowly increased instead of instantaneous mixing?
 - Dilution necessary before precipitation? Influence on microstructure?
 - What would be an appropriate diluent? (aprotic, polar, basic)
 - Acetone, EtOH+KOH, H₂O+KOH, ?
- What is the influence of temperature on both aramide dissolution and precipitation?
- Effect of nanofibers in epoxy on pot-life viscosity?
- How do the fibers align during infusion of dense structures?

Different ideas of epoxy composites for increasing K_{Ic}

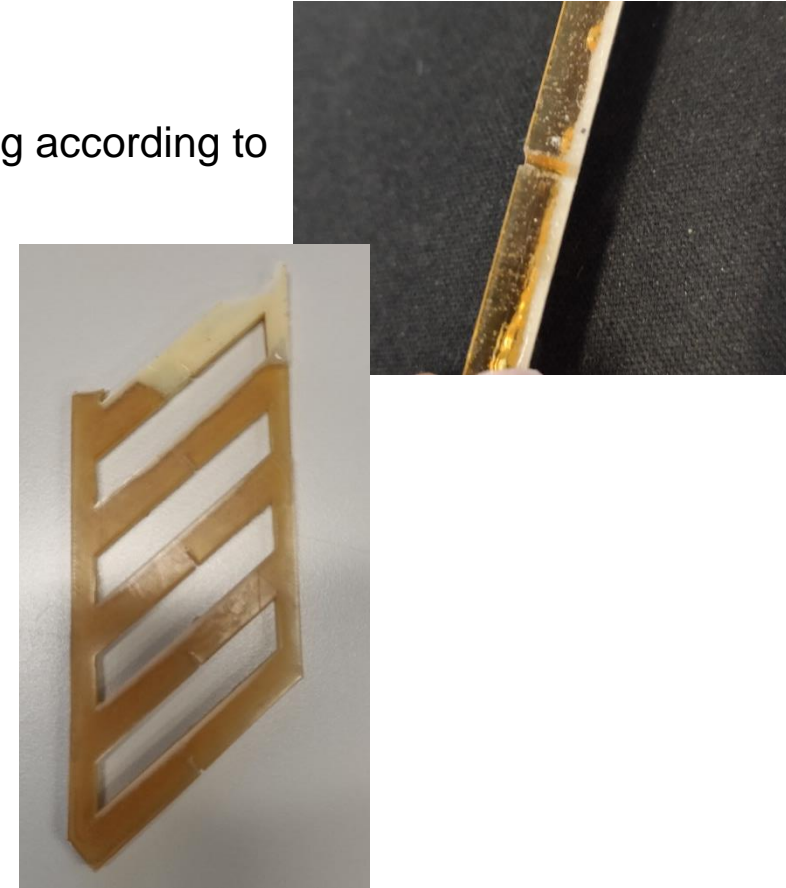
Pre-stressing (internal pressure)

- Idea: incorporate nascent UHMWPE (highly crystalline) particles into epoxy
- After curing, melt the UHMWPE \rightarrow lower crystallinity \rightarrow specific volume goes up \rightarrow pre-stress closes cracks
- Chain explosion \rightarrow improved adhesion?



UHMWPE in Epoxy (CTD-101K)

- **First trial**
 - Simply mixing GUR 4120 (commercial UHMWPE grade) with epoxy, degassing according to standard protocol & curing
 - White layer on top
 - Probably due to trapped air
- **Second trial**
 - Mixing GUR with liquid hardener (part B)
 - Degassed 10 mBar, 60 °C, 30 min → bubbling
 - Mixed with other components, degassed, cured, ultrasonic bath 2 min
 - Similar result
 - Air is entrapped since top level sank
- **Third trial**
 - Suspending GUR in ether (lower density → sediments)
 - Centrifugated, tip sonicated & centrifugated again
 - Now cured



Possible approaches to solve the problem

- **Prevent thermal stresses**
- → matching of thermal expansion coefficient to superconductor and metal (outside)

- **Increase heat capacity**
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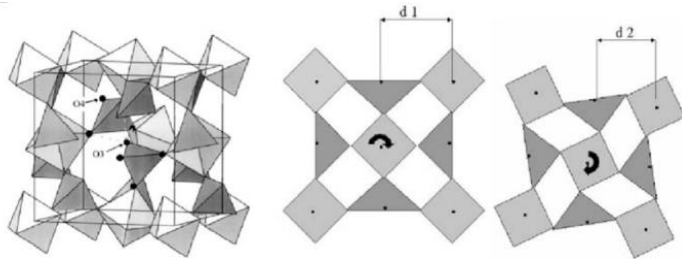
- **Increase K_{1c}**
- → prevention of cracking

- **Finding new superconductors with higher critical temperature**
- → not part of my work

Combined approach: heat capacity & thermal expansion match.

Zirconium tungstate (ZrW_2O_8)

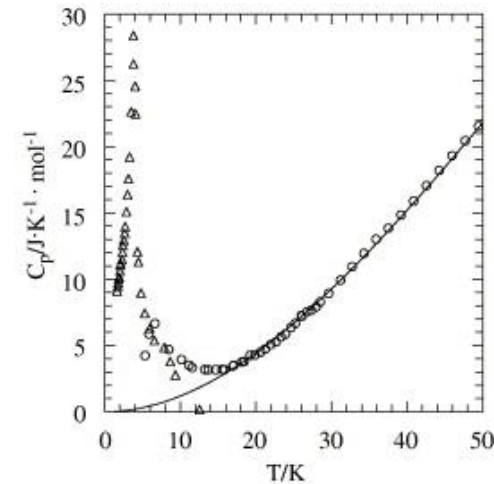
- *negative* coefficient of thermal expansion ($\alpha = -7.2 \cdot 10^{-6} \text{ K}^{-1}$) of ZrW_2O_8
- \rightarrow overall reduction in thermal expansion coefficient
- \rightarrow thermal stresses are distributed throughout epoxy rather than on interface superconductor/epoxy/metal



Schematics of Zirconium Tungstate and the RUM mechanism
10.1007/s10853-009-3692-4

+ Gadolinium Oxide (Gd_2O_3) composite

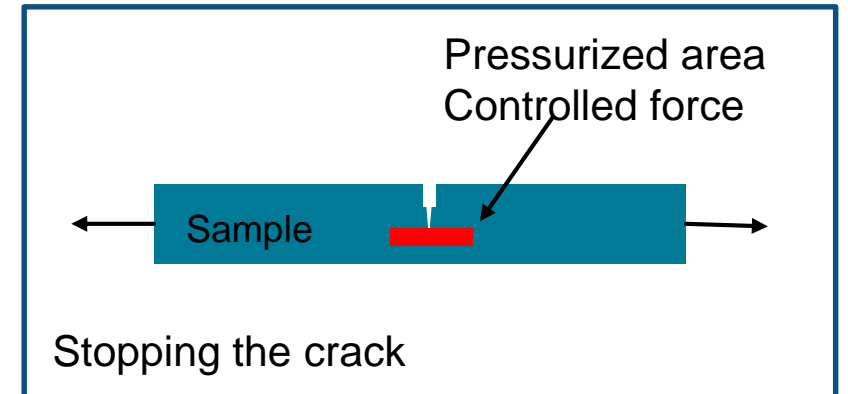
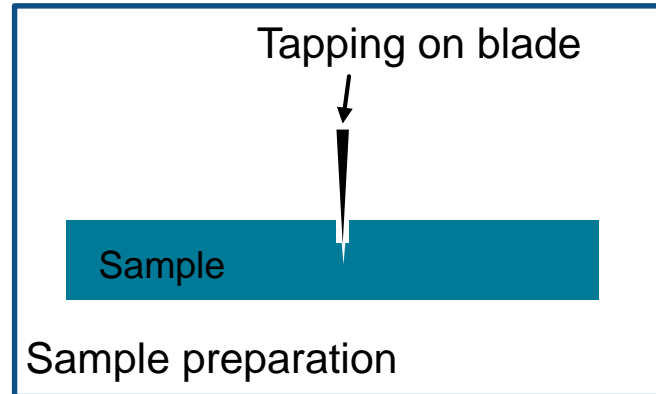
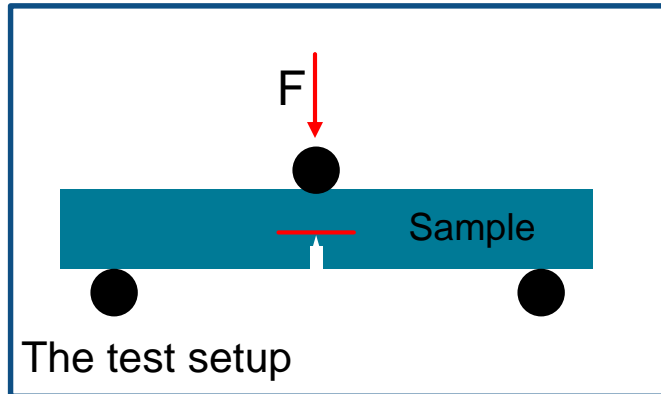
- Gadolinium oxide has anomaly in heat capacity at $\sim 3\text{K}$ \rightarrow where the magnet is operated
- Cracking and yielding would result in lower local temperature rise



Heat capacity of Gd_2O_3
10.1016/j.jct.2005.02.014

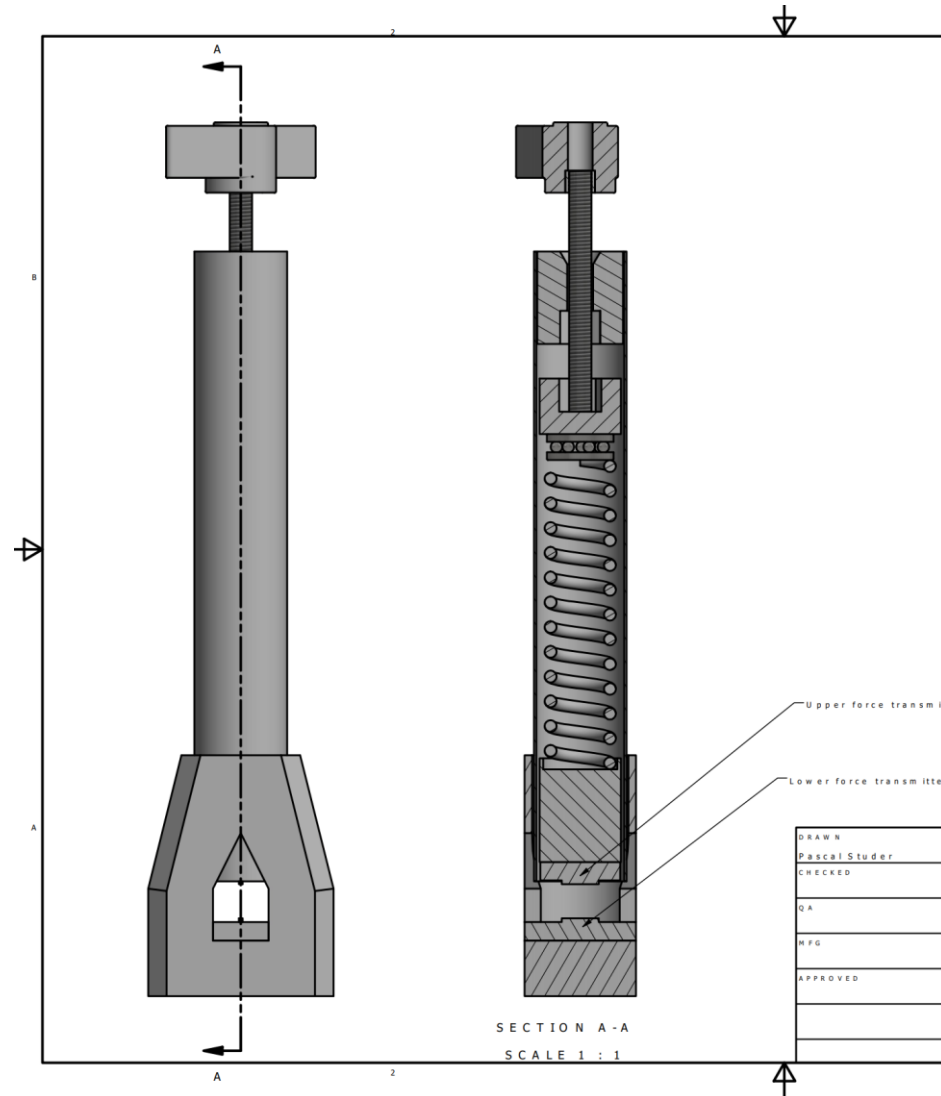
Measuring K_{Ic} for filled epoxy composites

- Single-etch notch bend samples (SENB) → difficult preparation



Measuring K_{Ic} for filled epoxy composites

- Device design
 - Controlled force
 - Most parts 3D printed
 - Except force transmitter (CNC)
- In progress...



Conclusion & Outlook, questions

- Further research
 - Explore toughening of epoxy composite with nascent UHMWPE and PTFE
 - Fabricate aramide nanofiber epoxy composite
 - Finish the sample notching device, obtain reliable K_{Ic} values
- Thanks
 - André Brem, Bernhard Auchmann and Theo Tervoort for their support
 - Fabian Gramm (ScopeM) for support with TEM imaging
 - Chris for helping with the design of the improved sample notcher

